NCCAVS Joint User Group Meeting Agenda (CMPUG, PAG, & TFUG)

Topic: Semiconductor Packaging Outside the Mainstream

Meeting Date: Wednesday, June 29, 2022
Time: 1:00 p.m.-4:15 p.m. PDT (TIME ZONE CONVERTER)

Co-Chairs:
Rob Rhoades, X-trinsic, zestrion@gmail.com
Jeff Shields, Resesas Electronics, jeffrey.shields@att.net
Paul Werbaneth, Ichor Systems, pfwerbaneth@gmail.com

The Northern California Chapter of the American Vacuum Society invites you to participate in a Joint User Group Meeting on Wednesday 30 June 2021. The meeting is being hosted by the NCCAVS CMP Users Group, the Plasma Applications Group, and the Thin Film Users Group.

FREE TO ALL ATTENDEES
Access the zoom link for the meeting through any of the 3 User Group web sites here:
https://nccavs-usergroups.avs.org/

AGENDA
1:00 p.m. Welcome and Acknowledgement of Meeting Sponsors, Joint User Group Meeting Co-Chairs: Rob Rhoades, Jeff Shields, Paul Werbaneth

1:15 p.m. **Andy Mackie**, Ph.D., Indium Corporation, *"Die-attach Materials Empowering Power Devices: Removing Heat and Supplying Power"*

1:45 p.m. **Steffen Kroehnert**, ESPAT Consulting, *"Packaging Advances in the OSAT, Foundry, and MEMS Markets with a Highlight on Europe"*

2:15 p.m. **David Harame**, Ph.D., SUNY Polytechnic, *"AIM Photonics Electronic-Photonic Technologies and Packaging outside the Mainstream"*

2:45 p.m. **Charles Woychik**, Ph.D., SkyWater Technology, *"On-Shoring the Next Generation of Advanced Packaging"*

3:15 p.m. **Melissa Grupen-Shemansky**, Ph.D., SEMI, "*Packaging Methods for Flexible Hybrid Electronics"*

3:45 p.m. **Amy Leong**, FormFactor, *"Test and Measurement Challenges and Opportunities for Chiplet Heterogeneous Integration"*

4:15 p.m. ADJOURN

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